FY09 Financial Results

Accomplishing Business Structural Reforms in FY09 & Engineering a V-shaped Recovery for FY10

April 26, 2010

Hitachi High-Technologies Corporation

President, Chief Executive Officer
Hidehito Obayashi, Ph.D.
Contents

FY09 Financial Results

Ⅰ Outline of FY09

Ⅱ FY10 Management Policy

Ⅲ FY10 Outlook

Ⅳ Data
Outline of FY09

(Note) YY/M denotes the year and month of the accounting period-end.
### Outline of FY09 (Highlights)

<table>
<thead>
<tr>
<th></th>
<th>Results</th>
<th>YoY</th>
<th>vs. Previous Forecast</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td></td>
<td>Increase/Decrease</td>
<td>Ratio</td>
</tr>
<tr>
<td><strong>Sales</strong></td>
<td>6,169</td>
<td>-1,581</td>
<td>-20%</td>
</tr>
<tr>
<td><strong>Operating Income</strong></td>
<td>-16</td>
<td>-165</td>
<td>-</td>
</tr>
<tr>
<td><strong>Ordinary Income</strong></td>
<td>-5</td>
<td>-170</td>
<td>-</td>
</tr>
<tr>
<td><strong>Net Income</strong></td>
<td>-28</td>
<td>-99</td>
<td>-</td>
</tr>
<tr>
<td><strong>Net Income per Share</strong></td>
<td>-20.55yen</td>
<td>-71.99yen</td>
<td>+17.98yen</td>
</tr>
<tr>
<td><strong>Cash Dividend per Share</strong></td>
<td>15.00yen</td>
<td>-15.00yen</td>
<td>+5.00yen</td>
</tr>
<tr>
<td><strong>ROE</strong></td>
<td>-1.2%</td>
<td>-4.2%</td>
<td>-</td>
</tr>
<tr>
<td><strong>FIV</strong></td>
<td>-122</td>
<td>-101</td>
<td>-</td>
</tr>
<tr>
<td><strong>FCF</strong></td>
<td>+141</td>
<td>+17</td>
<td>-</td>
</tr>
</tbody>
</table>

*Previous Forecast (Published values for Q3/Jan. 2010)*
Outline of FY09 (Explanation of Deviations)

vs. Previous Forecast

1. Sales/Operating Income (Published values for Q3/Jan. 2010)

Sales (600.0Ybn → 616.9Ybn +16.9Ybn)
- Electronic Device Systems: Investment recovery for semiconductor manufacturing equipment led to the growth of 2.1Ybn
- Life Sciences: Favorable performance of clinical analyzers led to the growth of 2.0Ybn
- Information Systems & Electronic Components: Sales growth in mobile phone business for the U.S. market led to the growth of 5.0Ybn
- Advanced Industrial Products: Price rise for materials and demand recovery for automotive components led to the growth of 7.8Ybn

Operating Income (-5.3Ybn → -1.6Ybn +3.7Ybn)
- Electronic Device Systems: Sales growth in semiconductor manufacturing equipment and recovery in production operation led to the growth of 2.2Ybn
- Life Sciences: Favorable performance of clinical analyzers led to the growth of 0.8Ybn
- Information Systems & Electronic Components: Sales growth in mobile phone business for the U.S. market led to the growth of 0.5Ybn

2. Business Structural Reforms (Published values for Q2/Oct. 2010)

<table>
<thead>
<tr>
<th></th>
<th>Previous Forecast</th>
<th>Results</th>
<th>Increase/Decrease</th>
</tr>
</thead>
<tbody>
<tr>
<td>Fixed Cost Reduction</td>
<td>-8.5Ybn</td>
<td>-8.5Ybn</td>
<td>±0Ybn</td>
</tr>
<tr>
<td>Proper disposition of employees</td>
<td>-1,450 employees</td>
<td>-1,500 employees</td>
<td>-50 employees</td>
</tr>
</tbody>
</table>
Outline of FY09 (Operating Income by Segment)

Operating Income

(100 million yen)

-300
0
300

09/3 10/3(e) 10/3

Life Sciences
194
19
19

Advanced Industrial Products
16
16
-27

Information Systems & Electronic Components
-53
-192
-192

Electronic Device Systems
150
158
158

YoY -%
-18%
-8%
-
-

(e) Previous Forecast (Published Values for Q3/Jan. 2010)
## Outline of FY09 (Income Statement in Summary)

For the year ended March 31, 2010

<table>
<thead>
<tr>
<th>Results</th>
<th>YoY Increase/Decrease</th>
<th>YoY Ratio</th>
</tr>
</thead>
<tbody>
<tr>
<td>Sales</td>
<td>6,169</td>
<td>-1,581</td>
</tr>
<tr>
<td>Cost of Sales</td>
<td>5,377</td>
<td>-1,330</td>
</tr>
<tr>
<td>Gross Profit</td>
<td>792</td>
<td>-250</td>
</tr>
<tr>
<td>Selling, General and Administrative Expenses</td>
<td>808</td>
<td>-85</td>
</tr>
<tr>
<td>Operating Income</td>
<td>-16</td>
<td>-165</td>
</tr>
<tr>
<td>Other Income</td>
<td>-19</td>
<td>-6</td>
</tr>
<tr>
<td>Other Expense</td>
<td>8</td>
<td>-2</td>
</tr>
<tr>
<td>Ordinary Income</td>
<td>-5</td>
<td>-170</td>
</tr>
<tr>
<td>Extraordinary Profit</td>
<td>6</td>
<td>-3</td>
</tr>
<tr>
<td>Extraordinary Loss</td>
<td>22</td>
<td>-13</td>
</tr>
<tr>
<td>Income Before Income Taxes and Minority Interests</td>
<td>-21</td>
<td>-160</td>
</tr>
<tr>
<td>Income Taxes</td>
<td>7</td>
<td>-61</td>
</tr>
<tr>
<td>Net Income</td>
<td>-28</td>
<td>-99</td>
</tr>
</tbody>
</table>

(100 million yen)
## Outline of FY09 (Balance Sheet in Summary)

### Year ended March 31, 2010

<table>
<thead>
<tr>
<th>Category</th>
<th>FY09</th>
<th>FY08</th>
<th>Change</th>
<th>FY09</th>
<th>FY08</th>
<th>Change</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Current Assets</strong></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Cash &amp; Deposits/Deposit to Hitachi Group Cash Management Fund</td>
<td>1,017</td>
<td>899</td>
<td>+118</td>
<td>1,017</td>
<td>899</td>
<td>+118</td>
</tr>
<tr>
<td>Notes &amp; Accounts Receivable</td>
<td>1,445</td>
<td>1,587</td>
<td>-98</td>
<td>1,445</td>
<td>1,587</td>
<td>-98</td>
</tr>
<tr>
<td>Inventories</td>
<td>572</td>
<td>676</td>
<td>-148</td>
<td>572</td>
<td>676</td>
<td>-148</td>
</tr>
<tr>
<td>Others</td>
<td>213</td>
<td>232</td>
<td>-30</td>
<td>213</td>
<td>232</td>
<td>-30</td>
</tr>
<tr>
<td><strong>Fixed Assets</strong></td>
<td>863</td>
<td>879</td>
<td>-7</td>
<td>863</td>
<td>879</td>
<td>-7</td>
</tr>
<tr>
<td>Tangible Fixed Assets</td>
<td>559</td>
<td>547</td>
<td>-25</td>
<td>559</td>
<td>547</td>
<td>-25</td>
</tr>
<tr>
<td>Intangible Fixed Assets</td>
<td>49</td>
<td>42</td>
<td>+7</td>
<td>49</td>
<td>42</td>
<td>+7</td>
</tr>
<tr>
<td>Investments &amp; Other Assets</td>
<td>254</td>
<td>242</td>
<td>+12</td>
<td>254</td>
<td>242</td>
<td>+12</td>
</tr>
<tr>
<td><strong>Total Assets</strong></td>
<td>4,110</td>
<td>4,291</td>
<td>-165</td>
<td>4,110</td>
<td>4,291</td>
<td>-165</td>
</tr>
<tr>
<td><strong>Current Liabilities</strong></td>
<td>1,557</td>
<td>1,571</td>
<td>-12</td>
<td>1,557</td>
<td>1,571</td>
<td>-12</td>
</tr>
<tr>
<td>Notes &amp; Accounts Payable</td>
<td>1,100</td>
<td>1,148</td>
<td>-38</td>
<td>1,100</td>
<td>1,148</td>
<td>-38</td>
</tr>
<tr>
<td>Others</td>
<td>457</td>
<td>513</td>
<td>-74</td>
<td>457</td>
<td>513</td>
<td>-74</td>
</tr>
<tr>
<td><strong>Fixed Liabilities</strong></td>
<td>259</td>
<td>258</td>
<td>-1</td>
<td>259</td>
<td>258</td>
<td>-1</td>
</tr>
<tr>
<td>Retirement and severance benefits</td>
<td>253</td>
<td>253</td>
<td>-1</td>
<td>253</td>
<td>253</td>
<td>-1</td>
</tr>
<tr>
<td>Others</td>
<td>6</td>
<td>5</td>
<td>-3</td>
<td>6</td>
<td>5</td>
<td>-3</td>
</tr>
<tr>
<td><strong>Net Assets</strong></td>
<td>2,294</td>
<td>2,341</td>
<td>-49</td>
<td>2,294</td>
<td>2,341</td>
<td>-49</td>
</tr>
<tr>
<td>Shareholder Capital</td>
<td>2,293</td>
<td>2,341</td>
<td>-56</td>
<td>2,293</td>
<td>2,341</td>
<td>-56</td>
</tr>
<tr>
<td>Assessments/Exchange Difference etc.</td>
<td>-1</td>
<td>-1</td>
<td>+7</td>
<td>-1</td>
<td>-1</td>
<td>+7</td>
</tr>
<tr>
<td>Minority Interests</td>
<td>3</td>
<td>3</td>
<td>+0</td>
<td>3</td>
<td>3</td>
<td>+0</td>
</tr>
</tbody>
</table>

(100 million yen)

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### Outline of FY09 (Cash Flow Statement in Summary)

<table>
<thead>
<tr>
<th>(100 million yen)</th>
<th>10/3</th>
<th>10/3</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Cash Flow from Operating Activities</strong></td>
<td><strong>+224</strong></td>
<td><strong>Cash Flow from Financing Activities</strong></td>
</tr>
<tr>
<td>Income Before Income Taxes and Minority Interests</td>
<td><strong>-21</strong></td>
<td>Dividends Paid</td>
</tr>
<tr>
<td>Depreciation and Amortization</td>
<td><strong>+96</strong></td>
<td>Others</td>
</tr>
<tr>
<td>Working Fund</td>
<td><strong>+175</strong></td>
<td>Effect of exchange rate changes</td>
</tr>
<tr>
<td>Income Taxes Paid/Refund</td>
<td><strong>+22</strong></td>
<td></td>
</tr>
<tr>
<td>Others</td>
<td><strong>-48</strong></td>
<td></td>
</tr>
<tr>
<td><strong>Cash Flow from Investing Activities</strong></td>
<td><strong>-83</strong></td>
<td></td>
</tr>
<tr>
<td>Capital Expenditures Proceeded from Sales / Purchase of Securities</td>
<td><strong>+8</strong></td>
<td></td>
</tr>
<tr>
<td>Capital Expenditures Proceeded from Sales / Purchase of Property and Equipment</td>
<td><strong>-71</strong></td>
<td></td>
</tr>
<tr>
<td>Others</td>
<td><strong>-20</strong></td>
<td></td>
</tr>
<tr>
<td><strong>Free Cash Flow</strong></td>
<td><strong>+141</strong></td>
<td></td>
</tr>
</tbody>
</table>

### Cash and Cash Equivalents

<table>
<thead>
<tr>
<th></th>
<th>10/3</th>
</tr>
</thead>
<tbody>
<tr>
<td>Cash and Cash Equivalents</td>
<td></td>
</tr>
<tr>
<td>At the Beginning of Year</td>
<td><strong>796</strong></td>
</tr>
<tr>
<td>Net Increase (Decrease)</td>
<td><strong>+106</strong></td>
</tr>
<tr>
<td>At the end of Term</td>
<td><strong>902</strong></td>
</tr>
</tbody>
</table>

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FY10 Management Policy
Changes in Segment Classification

Electronic Device Systems
- Process Equip.
- Metrology & Analysis Equip.
- LCD Manufacturing Equip.
- HD Manufacturing Equip.

NEW
- Process Equip.
- Metrology & Inspection Equip.
- Back-end & Assembly Equip.

Fine Technology Systems
- FPD Manufacturing Equip.
- HD Manufacturing Equip., Others

Science & Medical Systems
- General-purpose Analytical Instr.
- Electron Microscope
- Clinical Analyzer
- Biotechnology Product, Others

Life Sciences
- Biotechnology-related Business
- Medical-related Business

Industrial & IT Systems
- LiB Assembly Syst. etc.
- Automotive HDD etc.
- IT Solution
- Control Syst., Others

Information Systems & Electronic Components
- Information Syst.
- Assembly Syst.
- Semiconductor
- Media Devices

Chip Mounter

Advanced Industrial Products
- Industrial Material
- Electronic Material
- Optical-related Component

Advanced Industrial Products
- Industrial Material
- Electronic Device/Material
- Optical-related Component
- Fine Chemical, Others
FY10 Management Policy

Engineering a V-Shaped Recovery & Accelerating Growth Strategies

1. Steadily Implement Management Reforms
   - Develop the new business creation initiative
   - Transform into a truly global company
   - Strengthen trading functions
   - Strengthen cash flow management

2. Implement Business Strategy Adapted to the Changes in the Management Environment
Steadily Implement Management Reforms

Develop the new business creation initiative

- The New Business Creation Council
  - Core Technology Market
  - Submitting Themes & Selection
  - Feasibility Study
  - C Pro
  - Start of Business

C Pro: Corporate/Challenge Project

Transform into a true global company

- Develop New Global Business
- Expand Overseas Business
- Develop Emerging Markets
- Strengthen Globally-Capable Development & Manufacturing

Strengthen trading functions

- Established a new strategic planning division to control the trading divisions (Strategic Function)
- Established the Energy & Environmental Solutions Div. (Focus on Growing Fields)
- Promote transition to high value-added business (Selection & Focus)

Strengthen cash flow management

Introduction of new management system: Promote expansion and regeneration (Triple C) of consolidated cash flow

Consolidation
- WW business consolidation
- Promote integrated operation of manufacturing, sales and service

Cash-Flow
- Consolidated/divisional introduction of BS and CF

Challenge!
- Spiral up due to PDCA cycle
- New business creation initiative

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### Implement Business Strategy Adapted to the Changes in the Management Environment

<table>
<thead>
<tr>
<th>Segments</th>
<th>Management Environment</th>
<th>Business Strategy</th>
</tr>
</thead>
</table>
| Electronic Device Systems        | • Semiconductor Manufacturing Market not expected to return to past peak levels  
• Push ahead with technological development geared toward further scaling  
• Shift added value from front-end to back-end processes (Near physical limits for front-end scaling)                                                                                                                   | • Strengthen post-sales and move into non-semiconductor fields  
• Continue to introduce new products geared toward scaling  
• Cultivate back-end process and mounting systems as a source of revenue                                                                                                                                 |
| Fine Technology Systems          | • Intensifying price-competitiveness due to increasing China-oriented investment in the LCD manufacturing equipment market  
• Recover HD manufacturing market through enhanced density and increased production                                                                                                                                  | • Promote drastic cost cut  
• Shift resources to new products and businesses                                                                                                                                                               |
| Science & Medical Systems        | • Gentle growth in the electron microscope market, rising need for new material analysis  
• Single-digit growth in markets for in vitro diagnostics and DNA sequencers  
• Growth in immunodiagnostics but clinical chemistry field saturated                                                                                                                                              | • Create synergies with the electronic microscope/analytical business  
• Expand revenues by maintaining and deepening SCB*  
*System Collaboration Business  
• Expand business in growing markets such as genetics etc.                                                                                                                                                         |
| Industrial & IT Systems          | • Rapid growth in the eco-vehicle (EV, HEV etc.), energy and environment (solar, wind power etc.)  
• Rise in the emerging markets                                                                                                                                                                                       | • Focus on eco-vehicle, environment, and new energy-related markets  
• Expand high value added business through collaboration with proprietary product divisions  
• Expand business in the emerging market                                                                                                                                                                             |

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FY10 Outlook

(Note) YY/M denotes the year and month of the accounting period-end.
## FY10 Outlook (Highlights)

<table>
<thead>
<tr>
<th></th>
<th>FY10 Outlook</th>
<th>FY09 Results</th>
<th>YoY</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td></td>
<td>(100 million yen)</td>
<td></td>
</tr>
<tr>
<td></td>
<td>Increase/Decrease</td>
<td>Ratio</td>
<td></td>
</tr>
<tr>
<td>Sales</td>
<td>6,600</td>
<td>6,169</td>
<td>+431</td>
</tr>
<tr>
<td>Operating Income</td>
<td>172</td>
<td>-16</td>
<td>+188</td>
</tr>
<tr>
<td>Ordinary Income</td>
<td>175</td>
<td>-5</td>
<td>+180</td>
</tr>
<tr>
<td>Net Income</td>
<td>106</td>
<td>-28</td>
<td>+134</td>
</tr>
<tr>
<td>Net Income per Share</td>
<td>77.07yen</td>
<td>-20.55yen</td>
<td>+97.62yen</td>
</tr>
<tr>
<td>Cash Dividend per Share</td>
<td>20.00yen</td>
<td>15.00yen</td>
<td>+5.00yen</td>
</tr>
<tr>
<td>ROE</td>
<td>4.6%</td>
<td>-1.2%</td>
<td>+5.8%</td>
</tr>
<tr>
<td>FIV</td>
<td>-12</td>
<td>-122</td>
<td>+111</td>
</tr>
<tr>
<td>FCF</td>
<td>+115</td>
<td>+141</td>
<td>-26</td>
</tr>
</tbody>
</table>

FX Rate Estimate: 1USD= 85 yen
1EUR=125 yen
FY10 Outlook (Sales by Segment)

Sales

(100 million yen)

<table>
<thead>
<tr>
<th>Segment</th>
<th>10/3</th>
<th>11/3(e)</th>
<th>YoY</th>
</tr>
</thead>
<tbody>
<tr>
<td>Electronic Device Systems</td>
<td>6,169</td>
<td>6,600</td>
<td>+41%</td>
</tr>
<tr>
<td>Fine Technology Systems</td>
<td>584</td>
<td>825</td>
<td>+29%</td>
</tr>
<tr>
<td>Science &amp; Medical Systems</td>
<td>303</td>
<td>390</td>
<td>+8%</td>
</tr>
<tr>
<td>Industrial &amp; IT Systems</td>
<td>1,230</td>
<td>1,170</td>
<td>-8%</td>
</tr>
<tr>
<td>Advanced Industrial Products</td>
<td>2,922</td>
<td>1,135</td>
<td>-5%</td>
</tr>
<tr>
<td></td>
<td>1,231</td>
<td>3,150</td>
<td>+8%</td>
</tr>
</tbody>
</table>

(note) Elimination such as intersegment transactions etc. are included in the totals

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FY10 Outlook (Operating Income by Segment)

Operating Income

(100 million yen)

-16 172 13 24 21 25 142 119 18 9

10/3 11/3(e)

YoY

-16% -13% +5%

Electronic Device Systems
Fine Technology Systems
Science & Medical Systems
Industrial & IT Systems
Advanced Industrial Products

(note) Elimination such as intersegment transactions etc. are included in the totals
FY10 Outlook (Electronic Device Systems) ①

Semiconductor Manufacturing Equipment Market

-11%  +52%  +26%
10/3  11/3(e)  12/3(e)

Assembly Equipment Market

-54%  +46%  +15%
10/3(e)  11/3(e)  12/3(e)

(Source) Gartner (Mar. 2010)/HHT’s estimation
Previous forecast is based on Gartner (Sep. 2009)/HHT’s estimation

(Source) Created by HHT, based on Japan Robot Association’s data (Dec. 2009)
Previous forecast is based on published values for Q2/Oct. 2009
Changes in Order Received

(100 million yen)

09/Q1  10/3  637  -9%  11/3  825  +30%
10/Q1  126  +58%  212  +50%  215  +50%
10/Q2  154  +30%  188  +58%  221  +15%
10/Q3  200
10/Q4

FY10 Outlook (Electronic Device Systems) ②

(note) Step and scan system (FY08) is excluded for YoY data

steps and scans system (FY08) is excluded for YoY data
FY10 Outlook (Electronic Device Systems) ③

**FY10 Strategies**

1. Put in effort to growing fields
2. Take capital expenditures by strengthening technologies in scaling and in our unique areas of superiority

### Sales Change in Main Business (100 million yen)

- **10/3:**
  - Process Equip.: 244 (+20%)
  - Metrology & Inspection Equip.: 354 (+46%)
  - Back-end & Assembly Equip.: 225 (+63%)

- **11/3(e):**
  - Process Equip.: 825
  - Metrology & Inspection Equip.: 584 (+41%)
  - Back-end & Assembly Equip.: 204

### Sales Ratio by Fields (Front-end Equip.)

- **10/3:**
  - DRAM: 242
  - NAND: 138
  - Logic: 225
  - MPU: 10/3
  - Foundry: 10/3
  - Others: 11/3(e)

- **11/3(e):**
  - DRAM: 354 (+46%)
  - NAND: 225 (+63%)
  - Logic: 244 (+20%)
  - MPU: 825 (+41%)
  - Foundry: 584
  - Others: 204

**FY09:** Secured sales to MPU makers amid overall market contraction

**FY10:** Proportion of DRAM, NAND back to FY08 levels as memory device manufacturers resume investment
Strengthen Semiconductor Front-end Process Business

Resumption of Investment by Semiconductor Manufacturers (DRAM, NAND, MPU, ASSP)

Scaling Application
- OPC* growing more complex
- Introduction of DP* and other new technologies
- Adoption of HK/MG* and other new materials

Unique areas of superiority
- Response to growth fields such as HDD heads, embedded memory devices
- Correspond to causes of decreasing yield that are overt

- New CD-SEM application for computational lithography
- Precision metrology application along with DP compatibility
- Advanced Gate Etch Processing Equipment

- Non-volatile material etching
- Defect review SEM Expand applications using design data

[Effects]
- Shortened development period
- Improve productivity

New Products
- CD-SEM CG Series
- Design Based Metrology System DesignGauge Series
- EMCP Etcher E Series
- Defect Review SEM RS Series

* OPC : Optical Proximity Correction  *DP : Double Patterning  *HK/MG : High-k / Metal Gate

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Strengthen Semiconductor Back-end & Assembly Equipment Business

- Expand the back-end memory device market

**Expand NAND Application**
- High Capacity Application
  - High integration 3D mounting
- DRAM for High-end Products
  - High Speed Transmitting Application
    - New type package

**Adoption of thin film handling control system**
- High precision matching multi-layered application
- High speed bonding application for flip chip

**Effects**
- Cut production cost
- Improve quality & reliability

**Expand the SMT market**

**Diversification in Components**
- Multi-breed
- Becoming compact/thin

**High speed/precision Assembly**
- High productivity
- High reliability

**Expand to Emerging Areas**
- High quality
- Easy operation

**Adoption of easy arrangement and high speed head exchange application for multi-breed**
- State of the art mechatronics and control technology application
- Smart operation system for high efficient production

**Effects**
- Flexible production
- Reduce downtime

(NAND/SIP) DB-800 series
(DRAM) CM-700 series
Modular Mounter G4 G5
Printing Equip. P4

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FY10 Outlook (Fine Technology Systems) ①

**LCD Manufacturing Equipment Market**

- **10/3**: 1,770
- **11/3(e)**: 2,500
- **12/3(e)**: 3,500

**HD Manufacturing Equipment Market (HHT-related)**

- **10/3(e)**: 43
- **11/3(e)**: 113
- **12/3(e)**: 149

(Source) HHT's estimation based on SEAJ (Jan. 10) data
*Previous Forecast (Published Values for Q2/Oct. 2009)
FY10 Outlook (Fine Technology Systems)

Changes in Orders Received

<table>
<thead>
<tr>
<th>Quarter</th>
<th>Orders (100 million yen)</th>
<th>YoY Change</th>
</tr>
</thead>
<tbody>
<tr>
<td>09/Q1</td>
<td>31</td>
<td>-86%</td>
</tr>
<tr>
<td>09/Q2</td>
<td>46</td>
<td></td>
</tr>
<tr>
<td>09/Q3</td>
<td>79</td>
<td>+89%</td>
</tr>
<tr>
<td>09/Q4</td>
<td>106</td>
<td></td>
</tr>
<tr>
<td>10/Q1</td>
<td>111</td>
<td>+152%</td>
</tr>
<tr>
<td>10/Q2</td>
<td>84</td>
<td></td>
</tr>
<tr>
<td>10/Q3</td>
<td>145</td>
<td>+43%</td>
</tr>
<tr>
<td>10/Q4</td>
<td>119</td>
<td></td>
</tr>
</tbody>
</table>

10/3 262 -60% 11/3 459 +75% YoY

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FY10 Strategies

1. Expand business by raising competitiveness of existing products and introducing new products (new-type LCD assembly system / HD inspection equipment)
2. Acceleration of development of new business (OLED manufacturing / inspection equipment)
3. Shift to a business structure that adapts to market changes (strengthen sales power in China/improve cost-competitiveness)

Sales Changes in main products

- FPD Manufacturing Equip.: +29% YoY
- FPD-related Trading: -80%
- HD Manufacturing Equip., Others: +172%

Sales Ratio by Region (LCD-related equip.)

- Japan
- South Korea
- Taiwan Region
- China
- U.S. Europe etc.

- Make shift to Taiwan region and mainland China center of LCD-related investment in FY10
- Centering on the HD-related production improvements in FY09, in FY10 make investments to raise production significantly

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## HD inspection: New Concept Leads to Breakthrough

### Optical patterned media inspection system

Improve quality and reduce inspection cost by inspecting entire disk.

### Head element configuration inspection system

Improve productivity through inspections in the head assembly front-end process.

#### New concept device vs. Conventional device

<table>
<thead>
<tr>
<th>Feature</th>
<th>New concept device</th>
<th>Conventional device</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Inspection format</strong></td>
<td>All tracks</td>
<td>Skipped tracks</td>
</tr>
<tr>
<td><strong>Inspection area</strong></td>
<td>Total surface inspection (quality improvement)</td>
<td>1% of all tracks</td>
</tr>
<tr>
<td><strong>Consumables</strong></td>
<td>No need for inspection head (reduce inspection cost)</td>
<td>Use inspection head</td>
</tr>
</tbody>
</table>

#### Special features

- **Head assembly**
  - Measurement of head element configuration
- **Wafer**
  - Inspect in front-end Process (improve yield rate/reduce cost)

#### New concept device

- Create new markets for head inspection

### Expand market share 20% up
FY10 Outlook (Science & Medical Systems) (Analytical Instruments)

FY10 Strategies

1. Actively expand sales into growth markets (fuel cell, PV, LED, pharmacy, etc.)
2. Strengthen sales of electron microscope to biotech customers and general analysis systems to semiconductors and parts and materials customers

Overview of Analytical Instruments Market (HHT-related)

<table>
<thead>
<tr>
<th>Year</th>
<th>Elemental Analysis</th>
<th>Molecular Analysis</th>
<th>General-purpose Analysis</th>
<th>Separation Analysis</th>
</tr>
</thead>
<tbody>
<tr>
<td>CY09</td>
<td>1,000</td>
<td>2,000</td>
<td>3,000</td>
<td>100</td>
</tr>
<tr>
<td>CY10(e)</td>
<td>3,050</td>
<td>2,800</td>
<td>3,200</td>
<td>300</td>
</tr>
<tr>
<td>CY11(e)</td>
<td>3,200</td>
<td>2,850</td>
<td>3,200</td>
<td>350</td>
</tr>
</tbody>
</table>

CAGR 3%

Changes in Sales

<table>
<thead>
<tr>
<th>Year</th>
<th>Elemental Analysis</th>
<th>Molecular Analysis</th>
<th>General-purpose Analysis</th>
<th>Separation Analysis</th>
</tr>
</thead>
<tbody>
<tr>
<td>10/3</td>
<td>278</td>
<td>278</td>
<td>164</td>
<td>135</td>
</tr>
<tr>
<td>11/3(e)</td>
<td>413</td>
<td>413</td>
<td>278</td>
<td>278</td>
</tr>
</tbody>
</table>

YoY -7%

(Source) HHT’s estimation based on SDi Global Assessment Report 10.5 Edition data, etc.
FY10 Outlook (Science & Medical Systems) (Biotechnology Product / Clinical Analyzer)

FY10 Strategies

1. Promote SCB with leading companies (SCB: System Collaboration Business)
2. Promote equipment & reagent sales (China / Japan)

Overview of Biotechnology / Clinical Analyzer market (HHT-related)

- CAGR 4%
- 13,600 (CY09), 14,200 (CY10(e)), 14,800 (CY11(e))

Changes in Sales

- FY10 Outlook (Science & Medical Systems) (Biotechnology Product / Clinical Analyzer)
- CY09: 788 (Biotechnology Products), 613 (Biochemistry), 175 (Immunity), Others
- CY10(e): 758 (Biotechnology Products), 618 (Biochemistry), 140 (Immunity), Others
- CY11(e): 758 (Biotechnology Products), 618 (Biochemistry), 140 (Immunity), Others

(Source) HHT’s estimation based on Kalorama Information 6th Edition (08) data and others (reagents, equipment included)
What is Genetic Testing?
Genetic testing enables early detection and treatment of infectious disease and other illnesses by measuring the type of genes (nucleic acid) in pathogenic organisms and the level of contamination.

Special Features of the Technology

1. Complete automation of a complicated manual operations

Going Forward

• Promote collaboration with reagent manufacturers
• Plan to bring to market in FY11 (the research market)
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**Expansion of PV Equipment and Material Business (Establish strategic partnership with XeroCoat)**

**Business Target**
- **70% share of the AR coating equipment market (FY15)**
  - **Penetration rate**
    - 5%
    - 10%
    - 35%
    - 50%
  - **Equipment market size (unit)**
    - 6
    - 10
    - 14
    - 21
  - **Sales target (FY15)**
    - 10 Ybn

**Technology comparison**
- **Method**
  - XeroCoat, Inc.
  - Sputtering/CVD
  - Etching
  - Sol-Gel
- **Efficiency**
  - ○
  - ○
  - △
  - △
- **Easy processing**
  - ○
  - ×
  - ×
  - ×
- **Coating price**
  - 200¥/m²
  - 400¥/m²
  - 500¥/m²
  - 600¥/m²

**Before AR coating**
- **Cover glass**
  - 4% reflection
- **PV cell**
  - 96%

**After AR coating**
- **Cover glass**
  - 1% reflection
- **PV cell**
  - 99%

**3% increase in energy production**

**Synergy among Trading and Manufacturing Function**
- WW trading function + Self development / production technology
- Find potential venture company and establish partnership
- Material supply chain
- Development / production of new generation equipment (FPD manufacturing equip. div.)
Ⅳ Financial Data

(Note) YY/M denotes the year and month of the accounting period-end.
### Quarterly Results

<table>
<thead>
<tr>
<th></th>
<th>08/Q1</th>
<th>08/Q2</th>
<th>08/Q3</th>
<th>08/Q4</th>
<th>09/Q1</th>
<th>09/Q2</th>
<th>09/Q3</th>
<th>09/Q4</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Sales</strong></td>
<td>1,829</td>
<td>2,404</td>
<td>1,633</td>
<td>1,883</td>
<td>1,325</td>
<td>1,492</td>
<td>1,451</td>
<td>1,901</td>
</tr>
<tr>
<td><strong>Operating Income</strong></td>
<td>19</td>
<td>106</td>
<td>23</td>
<td>1</td>
<td>-38</td>
<td>-38</td>
<td>4</td>
<td>56</td>
</tr>
<tr>
<td><strong>Ordinary Income</strong></td>
<td>26</td>
<td>113</td>
<td>30</td>
<td>-4</td>
<td>-32</td>
<td>-37</td>
<td>8</td>
<td>57</td>
</tr>
<tr>
<td><strong>Net Income</strong></td>
<td>-2</td>
<td>78</td>
<td>20</td>
<td>-25</td>
<td>-20</td>
<td>-33</td>
<td>-3</td>
<td>28</td>
</tr>
</tbody>
</table>

### Sales by Segment

<table>
<thead>
<tr>
<th>Segment</th>
<th>08/Q1</th>
<th>08/Q2</th>
<th>08/Q3</th>
<th>08/Q4</th>
<th>09/Q1</th>
<th>09/Q2</th>
<th>09/Q3</th>
<th>09/Q4</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Electronic Device Systems</strong></td>
<td>250</td>
<td>612</td>
<td>327</td>
<td>494</td>
<td>200</td>
<td>233</td>
<td>238</td>
<td>470</td>
</tr>
<tr>
<td><strong>Life Sciences</strong></td>
<td>248</td>
<td>243</td>
<td>213</td>
<td>273</td>
<td>207</td>
<td>233</td>
<td>217</td>
<td>297</td>
</tr>
<tr>
<td><strong>Information Systems &amp; Electronic Components</strong></td>
<td>443</td>
<td>616</td>
<td>420</td>
<td>558</td>
<td>352</td>
<td>398</td>
<td>384</td>
<td>462</td>
</tr>
<tr>
<td><strong>Advanced Industrial Products</strong></td>
<td>888</td>
<td>933</td>
<td>673</td>
<td>558</td>
<td>566</td>
<td>628</td>
<td>613</td>
<td>672</td>
</tr>
</tbody>
</table>
## Capital Expenditure/Depreciation Costs/R&D

<table>
<thead>
<tr>
<th></th>
<th>09/3</th>
<th>10/3</th>
<th>YoY</th>
<th>11/3(e)</th>
<th>YoY</th>
</tr>
</thead>
<tbody>
<tr>
<td>Capital Expenditure</td>
<td>122</td>
<td>94</td>
<td>-23%</td>
<td>118</td>
<td>+26%</td>
</tr>
<tr>
<td>Depreciation Costs</td>
<td>95</td>
<td>96</td>
<td>+1%</td>
<td>103</td>
<td>+8%</td>
</tr>
<tr>
<td>R&amp;D</td>
<td>215</td>
<td>193</td>
<td>-10%</td>
<td>222</td>
<td>+15%</td>
</tr>
</tbody>
</table>

*Capital Expenditure is based on an acquisition bases*

### Context (FY09)

- **Capital Expenditure**: 2.9Ybn decrease
- **Extension and renovation of Naka Works**
- **R&D**: 2.2Ybn decrease
- **Development of elemental technology in Electronic Device Systems and Life Sciences**
## Restatement of FY09 Sales by Segment

### (unit: 100 million yen)

<table>
<thead>
<tr>
<th>No.</th>
<th>Segment</th>
<th>Sub-Segment</th>
<th>FY09 Result</th>
<th>(b)-(a)</th>
<th>Ref. No. to be applied</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td></td>
<td></td>
<td>(a) Old</td>
<td>(b) New</td>
<td></td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td>Total</td>
<td></td>
<td></td>
</tr>
<tr>
<td>1</td>
<td>Electronic Device Systems</td>
<td>Process Equip.</td>
<td>201</td>
<td>204</td>
<td>3</td>
</tr>
<tr>
<td>2</td>
<td></td>
<td>Metrology &amp; Analysis Equip.</td>
<td>519</td>
<td>242</td>
<td>-277</td>
</tr>
<tr>
<td>3</td>
<td></td>
<td>Metrology &amp; Inspection Equip.</td>
<td>0</td>
<td>138</td>
<td>138</td>
</tr>
<tr>
<td>4</td>
<td></td>
<td>Back-end &amp; Assembly Equip.</td>
<td>138</td>
<td>138</td>
<td></td>
</tr>
<tr>
<td>5</td>
<td>Fine Technology Systems</td>
<td>LCD Manufacturing Equip.</td>
<td>224</td>
<td>272</td>
<td>48</td>
</tr>
<tr>
<td>6</td>
<td></td>
<td>FPD Manufacturing Equip.</td>
<td>17</td>
<td>31</td>
<td>14</td>
</tr>
<tr>
<td>7</td>
<td></td>
<td>Total</td>
<td>720</td>
<td>564</td>
<td>-136</td>
</tr>
<tr>
<td>8</td>
<td></td>
<td>Others</td>
<td>180</td>
<td>0</td>
<td>-180</td>
</tr>
<tr>
<td>9</td>
<td></td>
<td>Total</td>
<td>1,141</td>
<td>887</td>
<td>-254</td>
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<tr>
<td>10</td>
<td>Life Sciences</td>
<td>Biotecnology-related Biz.</td>
<td>164</td>
<td></td>
<td></td>
</tr>
<tr>
<td>11</td>
<td>Science &amp; Medical Systems</td>
<td>General-purpose Analytical Instr.</td>
<td>213</td>
<td>278</td>
<td>229</td>
</tr>
<tr>
<td>12</td>
<td></td>
<td>Electron Microscope</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>13</td>
<td></td>
<td>Medical-related Biz.</td>
<td>613</td>
<td></td>
<td></td>
</tr>
<tr>
<td>14</td>
<td></td>
<td>Clinical Analyzer</td>
<td>708</td>
<td>175</td>
<td>80</td>
</tr>
<tr>
<td>15</td>
<td></td>
<td>Biotechnology Product, Others</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>16</td>
<td></td>
<td>Others</td>
<td>34</td>
<td>0</td>
<td>-34</td>
</tr>
<tr>
<td>17</td>
<td>Information Systems &amp; Electronic Components</td>
<td>Assembly Syst.</td>
<td>162</td>
<td>88</td>
<td>-74</td>
</tr>
<tr>
<td>18</td>
<td></td>
<td>LIB Assembly Syst. etc.</td>
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<td></td>
<td></td>
</tr>
<tr>
<td>19</td>
<td></td>
<td>Automotive HDD etc.</td>
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<td>244</td>
<td>244</td>
</tr>
<tr>
<td>20</td>
<td></td>
<td>IT Solution</td>
<td>733</td>
<td>491</td>
<td>-242</td>
</tr>
<tr>
<td>21</td>
<td></td>
<td>Semiconductor</td>
<td>193</td>
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<td>-193</td>
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<tr>
<td>22</td>
<td></td>
<td>Media Devices</td>
<td>176</td>
<td>0</td>
<td>-176</td>
</tr>
<tr>
<td>23</td>
<td></td>
<td>Others</td>
<td>331</td>
<td>408</td>
<td>77</td>
</tr>
<tr>
<td>24</td>
<td>Advanced Industrial Products</td>
<td>Industrial Material</td>
<td>1,168</td>
<td>1,217</td>
<td>49</td>
</tr>
<tr>
<td>25</td>
<td></td>
<td>Electric Material</td>
<td>526</td>
<td>798</td>
<td>272</td>
</tr>
<tr>
<td>26</td>
<td></td>
<td>Electric Device/Material</td>
<td>357</td>
<td>370</td>
<td>13</td>
</tr>
<tr>
<td>27</td>
<td></td>
<td>Optical-related Component</td>
<td>427</td>
<td>537</td>
<td>110</td>
</tr>
<tr>
<td>28</td>
<td></td>
<td>Fine Chemical, Others</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>29</td>
<td>Company Total</td>
<td></td>
<td>6,169</td>
<td>6,169</td>
<td>0</td>
</tr>
</tbody>
</table>
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FY09 Financial Results

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For further information
Hiroyuki Kato
Manager
Public & Investor Relations Group
Secretary’s Office
TEL: +81-3-3504-5138  FAX: +81-3-3504-5943
E-mail: kato-hiroyuki@nst.hitachi-hitec.com